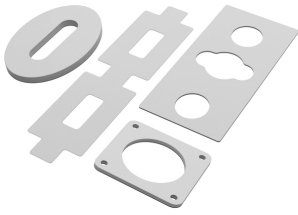


Data sheet Product GEL F 50 25



Accessories for electronic components>Thermal interface material>Heat conductive foam and gel foils

- silicone-free material, therefore no outgassing of silicone-containing ingredients
- ap filler function to compensate larger unevennesses and device differences
- very good thermal and electrical properties
- soft and easily compressible thermal conductive foil
- cuts, punched parts and special contours according to your drawing specifications

Features

material thickness:	2.5 mm
version:	silicone-free thermal conductive foils
colour:	white
density:	3.1 g/cm ³
hardness:	75 Shore 00
thermal conductivity:	5 W/m·K
specific thermal resistance:	0.64°C cm ² /W [1mm @ 30psi]
temperature range:	-40°C... +125°C
elongation:	50 %
kompression_1mm30psi:	20 % [1mm@30psi]
volume resistance:	10 ¹¹ Ω·m
dielectric constant:	5,4 [1 GHz]
dielectric strength:	2 kV/mm
class of inflammability:	UL 94 V-0
type of delivery:	<ul style="list-style-type: none"> • plates, usable area 200x400mm • other dimensions upon request